

Overview

The LC8213 is a IC that compresses (codes) and expands (decodes) binary image data used for facsimiles, etc. This LC8213 can be used in office automation equipment such as G3/G4 facsimiles, image file systems, digital photocopiers, and workstations.

The coding method is based on the MH (Modified Huffman), MR (Modified Relative Element Address Designate), and MMR (Modified MR) coding methods regulated by CCITT T.4 and T.6.

Features

- CCITT T.4 and T.6 MH, MR, MMR coding methods
- Compatible with G3 and G4 facsimiles
- No. of main scanning direction pixels Max.
 64k bits
- · Line skip mode
- · 8/16 bit image memory bus, 8-bit CPU bus
- Transfer of data between CPU bus and image memory bus
- DMA transfer function between image memory and I/O device
- System clock Max. 20MHz
- CMOS low power consumption

Package Dimensions

(unit : mm) 3174-QIP80E



Specifications

Absolute maximum ratings at $Ta = 25^{\circ}C$, $V_{SS} = 0V$

| Parameter | | Symbol | Condition | Rating | Unit |
|------------------------------|----------------|---------------------------------|------------|--------------------------------|------|
| Maximum supply voltage | | V _{DD} max | | - 0.3 to + 7.0 | V |
| Input/output voltage | | V _I , V _O | | – 0.3 to V _{DD} + 0.3 | v |
| Maximum | | Pd max | Ta≤70°C | 350 | mW |
| Operation ambie | nt temperature | Topr | | - 30 to + 70 | °C |
| Storage ambient | temperature | Tstg | | – 55 to + 125 | °C |
| Resistance against solder | Manual solder | | 3 seconds | 350 | °C |
| heat | Reflow | | 10 seconds | 235 | °C |

SANYO Electric Co., Ltd. Semiconductor Business Headquarters TOKYO OFFICE Tokyo Bldg., 1-10, 1 Chome, Ueno, Taito-ku, TOKYO, 110 JAPAN

Allowable Operating ranges at Ta = -30 to +70 °C, $V_{SS} = 0$ V

| Parameter | | | Rating | | | |
|------------------------|-----------------|-----|--------|-----------------|------|--|
| | Symbol | min | typ | max | Unit | |
| Supply voltage | V _{DD} | 4.5 | 5.0 | 5.5 | V | |
| Input voltage range | V _{IN} | 0 | | V _{DD} | V | |

DC Characteristics at Ta = -30 to +70°C, V_{SS} = 0V, V_{DD} = 4.5 to 5.5V

| _ | | | | Rating | | |
|---------------------------|------------------|---------------------------------|-------|--------|-------|------|
| Parameter | Symbol | Condition | | typ | max | Unit |
| Input high level voltage | ViH | TTL compatible | 2.2 | | | ν |
| Input low level voltage | V _{IL} | TTL compatible | | | 0.8 | V |
| Input leak current | ار | $V_{IN} = V_{SS}, V_{DD}$ | - 25 | | + 25 | μA |
| Output high level voltage | V _{OH} | I _{OH} = - 3mA | 2.4 | | | V |
| Output low level voltage | V _{OL} | I _{OL} = 3mA | | | 0.4 | V |
| Output leak current | l _{oz} | During high impedance output | - 100 | | + 100 | μΑ |
| Oscillation frequency | f _{osc} | CLK | | | 20 | MHz |
| Current consumption | I _{DD} | | | 15 | 30 | mA |

AC Characteristics

Clock Reset Timing

| Denemater | C | | Rating | |
|------------------------|--------|--------|--------|--------|
| Parameter | Symbol | min | typ | Unit |
| Clock cycle time | tCLK | 50 | | ns |
| Clock low level width | tCKL | 15 | | ns |
| Clock high level width | tCKH | 15 | | ns |
| Reset pulse width | tRSTW | 6 tCLK | | ns |

CPU Interface

| D | | | Rating | | |
|-----------------------|--------|-----|--------|----------------|------|
| Parameter | Symbol | min | typ | max | Unit |
| Address setup time | tAS | 20 | | | ns |
| Address hold time | tAH | 10 | | | ns |
| Read pulse width | tRW | 100 | | | ns |
| Read data delay time | tRD | | | 100 | ns |
| Read data hold time | tRH | 10 | | | ns |
| Write pulse width | tWW | 100 | | | ns |
| Write data setup time | tDS | 20 | | | ns |
| Write data hold time | tWH | 10 | | | ns |
| DACK setup time | tDAS | 20 | | | ns |
| DACK hold time | tDAH | 10 | | | ns |
| DREQ delay time | tDRQ | | | 2 tCLK + 70 | ns |

Image Memory Interface

| - | | | Rating | | | |
|-----------------------------------|--------|------------|--------|---------|------|--|
| Parameter | Symbol | min | typ | max | Unit | |
| AEN 👃 delay time | tAEL | | | 70 | ns | |
| AEN ↑ delay time | tAEH | | | 70 | ns | |
| AST ↑ delay time | tASH | | | 70 | ns | |
| AST 👃 delay time | tASL | | | 70 | ns | |
| Control signal valid delay time | tRWV | | | 70 | ns | |
| Control signal invalid delay time | tRWH | | | 70 | ns | |
| MRD, IORD 👃 delay time | tRDL | | | 70 | ns | |
| MRD, IORD ↑ delay time | tRDH | | | 70 | ns | |
| MWR, IOWR 👃 delay time | tWRL | | | 70 | ns | |
| MWR, IOWR ↑ delay time | tWRH | | | 70 | ns | |
| UDE, LDE 👃 delay time | tDEL | | | 70 | ns | |
| UDE, LDE ↑ delay time | tDEH | | | 70 | ns | |
| MDEN 👃 delay time | tMDL | | | 70 | ns | |
| MDEN ↑ delay time | tMDH | | | 70 | ns | |
| Address valid delay time | tMAV | | | 100 | ns | |
| Address hold time | tMAH | 25 | | | ns | |
| Read data setup time | tDSR | 10 | | | ns | |
| Read data hold time | tDHR | 0 | | | ns | |
| Write data delay time | tDDW | | | 80 | ns | |
| Write data hold time | tDHW | 10 | | | ns | |
| BREQ ↑ delay time (for IDREQ ↑) | tBRH | 2 tCLK | | 4 tCLK | ns | |
| | | + 20 | | + 70 | | |
| BREQ 👃 delay time | tBRL | _ | | 70 | ns | |
| IDACK 👃 delay time (for BACK 👃) | tDACD | 3 tCLK | | 13 tCLK | ns | |
| | | + 20 | | + 70 | | |
| IDACK ↓ delay time (for CLK ↑) | tDACL | | | 70 | ns | |
| IDACK ↑ delay time | tDACH | _ _ | | 70 | ns | |
| DTC ↑ delay time | tDTCH | | | 70 | ns | |
| DTC ↓ delay time | tDTCL | | | 70 | ns | |
| READY setup time | tRDYS | 30 | | | ns | |
| READY hold time | tRDYH | 30 | | | ns | |

Block Diagram



· CPU interface

This is an interface circuit with the general purpose 8-bit CPU. The operation mode can be set, etc., by accessing the interface register and parameter register.

· Sequence controller

Each block is controlled by the coded and decoded process algorithm.

Coding section

The change points of the pixels are detected and judged, and a code in each mode is generated. The coded data is transferred to the data bus via the FIFO (EFIFO) for 8-bit×4-word coding.

· Decoding section

The coded data in each mode is judged and the reproduced pixel data is generated. The coded data is transferred to the data bus via the FIFO (DFIFO) for decoding.

Image memory interface

Reading and writing of the image memory and control of the DMA transfer on the image memory bus is performed.

Pin Assignment

- I : Input pin
- 0 : Output pin
- B : Bidirectional pin
- P : Power pin
- $NC \ : Not \ connected$

| I | | |
|--------|---|---------------|
| 65 | | a ⁴° |
| | | |
| | | |
| | 0 | |
| B0 === | | P 25 |
| B0 | | <u> </u> 25 |

| No. | Pin name | Туре |
|-----|-----------------|------|
| 1 | CS | I |
| 2 | RD | Ι |
| 3 | WR | Ι |
| 4 | A2 | I |
| 5 | A1 | I |
| 6 | A0 | Ι |
| 7 | V _{DD} | Р |
| 8 | | NC |
| 9 | D7 | В |
| 10 | D6 | В |
| 11 | D5 | В |
| 12 | D4 | В |
| 13 | V _{SS} | Р |
| 14 | D3 | В |
| 15 | D2 | В |
| 16 | D1 | B |
| 17 | D0 | В |
| 18 | | NC |
| 19 | V _{DD} | Р |
| 20 | IREQ | 0 |
| 21 | DREQ | 0 |
| 22 | DACK | Ι |
| 23 | | NC |
| 24 | | NC |
| 25 | | NC |
| 26 | | NC |
| 27 | RESET | Ι |
| 28 | CLK | Ι |
| 29 | V _{SS} | Р |
| 30 | TEST4 | Ι |

| No. | Pin name | Туре |
|-----|-----------------|------|
| 31 | V _{DD} | P. |
| 32 | TEST3 | I |
| 33 | TEST2 | I |
| 34 | TEST1 | I |
| 35 | TEST0 | I |
| 36 | | NC |
| 37 | BREQ | 0 |
| 38 | BACK | I |
| 39 | IDREQ | I |
| 40 | IDACK | 0 |
| 41 | AEN | 0 |
| 42 | AST | 0 |
| 43 | MDEN | 0 |
| 44 | MRD | 0 |
| 45 | MWR | 0 |
| 46 | IORD | 0 |
| 47 | IOWR | 0 |
| 48 | LDE | 0 |
| 49 | ŪDE | 0 |
| 50 | READY | I |
| 51 | DTC | 0 |
| 52 | V _{SS} | Р |
| 53 | V _{DD} | Р |
| 54 | MA23 | 0 |
| 55 | MA22 | 0 |
| 56 | MA21 | 0 |
| 57 | MA20 | 0 |
| 58 | MA19 | 0 |
| 59 | MA18 | 0 |
| 60 | MA17 | 0 |

| No. | Pin name | Туре |
|-----|-----------------|------|
| 61 | MA16 | 0 |
| 62 | MA/MD15 | 0 |
| 63 | V _{SS} | Р |
| 64 | MA/MD14 | В |
| 65 | MA/MD13 | В |
| 66 | MA/MD12 | В |
| 67 | MA/MD11 | В |
| 68 | MA/MD10 | В |
| 69 | MA/MD9 | В |
| 70 | MA/MD8 | В |
| 71 | MA/MD7 | В |
| 72 | V _{SS} | Р |
| 73 | V _{DD} | Р |
| 74 | MA/MD6 | В |
| 75 | MA/MD5 | В |
| 76 | MA/MD4 | В |
| 77 | MA/MD3 | В |
| 78 | MA/MD2 | В |
| 79 | MA/MD1 | В |
| 80 | MA/MD0 | В |

| Pin Descriptions |
|-------------------------|
| CPU Interface |

| Pin name | Pin No. | 1/0 | Descriptions |
|-----------|---------|----------|---|
| <u>cs</u> | 1 | 1 | Chip select for the CPU to access the LC8213 (low active). |
| RD | 2 | | Read. Set to "L" when the CPU is to read out the LC8213 register. |
| WR | 3 | 1 | Write. Set to "L" when the CPU is to write to the LC8213 register. |
| A2 | 4 | 1 | Address input for when the CPU accesses LC8213. |
| A1 | 5 | | |
| A0 | 6 | | |
| D7 | 9 | 1/0 | Bidirectional 8-bit data bus |
| D6 | 10 | 3 states | |
| D5 | 11 | | |
| D4 | 12 | | |
| D3 | 14 | | |
| D2 | 15 | | |
| D1 | 16 | | |
| D0 | 17 | | · · · |
| IREQ | 20 | 0 | Interrupt request signal for the CPU. By reading out the INTR (interrupt request register) the CPU can find the cause of the interruption. IREQ is set to "L" when the CPU reads INTR. |
| DREQ | 21 | 0 | DMA request signal for the external DMA controller. This will be set to "H" in the following cases. * Data exists in the EFIFO during the coding processes. * An empty space exists in the DFIFO during decoding processes. * The DBUF can read/write during data transfer between the image memory bus and CPU bus. |
| DACK | 22 | I | DMA acknowledge signal from the external DMA controller. If DACK is set to "L" during coding or decoding, EFIFO and DFIFO will be accessed. DBUF will be accessed if DACK is set to "L" during data transfer between the image memory bus and CPU bus. |

Image Memory Interface

| Pin name | Pin No. | I/O | Descriptions |
|----------|---------|----------|--|
| MA23 | 54 | 0 | High-order 8-bit address of the image memory. |
| MA22 | 55 | 3 states | |
| MA21 | 56 | | |
| MA20 | 57 | | |
| MA19 | 58 | ļ | |
| MA18 | 59 | | |
| MA17 | 60 | 1 | |
| MA16 | 61 | | |
| MA/MD15 | 62 | 1/0 | Low-order 16-bit address and 16-bit data bus for the image memory. |
| MA/MD14 | 64 | 3 states | |
| MA/MD13 | 65 | | |
| MA/MD12 | 66 | | |
| MA/MD11 | 67 | | |
| MA/MD10 | 68 | | |
| MA/MD9 | 69 | | |
| MA/MD8 | 70 | | |
| MA/MD7 | 71 | | |
| MA/MD6 | 74 | | |
| MA/MD5 | 75 | | |
| MA/MD4 | 76 | | |
| MA/MD3 | 77 | | |
| MA/MD2 | 78 | | |
| MA/MD1 | 79 | | |
| MA/MD0 | 80 | | |
| AEN | 41 | 0 | This is set to "L" when the LC8213 is the bus master to the image memory. If AEN = "H", MA/MD, MRD, MWR, IORD, IOWR, UDE and LDE will be a HiZ output. |
| AST | 42 | 0 | This signal indicates that an address is being output to MA/MD15 to MA/MD0. |
| MDEN | 43 | 0 | This signal indicates that the LC8213 is using MA/MD15 to MA/MD0 as data buses. |
| UDE | 49 | 0 | This signal indicates that the high-order bits of the data bus are being |
| | | 3 states | used. |
| LDE | 48 | 0 | This signal indicates that the low-order bits of the data bus are being |
| | _ | 3 states | used. |
| MRD | 44 | 0 | This is set to "L" when data is being read out of the image memory. |
| | | 3 states | |
| MWR | 45 | 0 | This is set to "L" when data is being written into the image memory. |
| | -3 | 3 states | i interest of a men data is being written into the image meniory. |

Continued on next page.

LC8213

Continued from preceding page.

| Pin name | Pin No. | 1/0 | Descriptions |
|----------|---------|----------|---|
| IORD | 46 | 0 | This is set to "L" when data is being read out of the I/O device. |
| | [| 3 states | |
| TOWR | 47 | 0 | This is set to "L" when data is being written into the I/O device. |
| | | 3 states | |
| BREQ | 37 | 0 | This signal is used for the LC8213 to request usage rights from the |
| | | | image memory bus. |
| BACK | 38 | - | Input signal allowing the LC8213 to use the image memory bus. |
| IDREQ | 39 | ι | Input signal used for the I/O device to request DMA from the LC8213. |
| IDACK | 40 | 0 | DMA acknowledge signal from LC8213. |
| READY | 50 | 1 | This signal is used to delay the read/write signal when using low speed |
| | | | image memory or an I/O device. |
| DTC | 51 | 0 | This signal indicates that the DMA transfer has been completed. |

Others

| Pin name | Pin No. | I/O | Descriptions | |
|-----------------|--------------------------|----------|--------------------------------|--|
| CLK | 28 | I | External clock (Max. 20MHz) | |
| RESET | 27 | 1 | Reset | |
| TESTO | 35 | <u> </u> | For testing | |
| TEST1 | 34 | | This is normally fixed to "L". | |
| TEST2 | 33 | | | |
| TEST3 | 32 | | | |
| TEST4 | 30 | | | |
| V _{DD} | 7, 9, 31, 53, 73 | | Power supply (+ 5V) | |
| V _{SS} | 13, 29, 52, 63, 72 | | GND | |

Explanation of Function

· Coding method

The coding method follows the CCITT T.4, T.6 MH, MR and MMR coding methods that are the standard for the G3 and G4 facsimiles.

· Processing mode

A maximum of 64k lines for processing can be set, and processing per block is possible. Processing per line is also possible. The coding and decoding FIFOs are built-in, and coding and decoding can be performed alternately for several lines at a time.

When coding, the LC8213 reads the image data in order from the start address of the image memory set in the register. This data is coded and written into the coding FIFO. When the set number of lines have been processed, the CPU is interrupted.

When decoding, the LC8213 reads the coded data from the decoding FIFO, reproduces the image data, and writes it into the image memory. When the set number of lines have been processed or a decoding error occurs, the CPU is interrupted.

· Line skip mode

This mode allows the coded amount of blank lines to be decreased to half of the minimum transmission bits. The line skip bit (blank line judgment bit) is added to the end of the EOL code, and a fill bit is added to the blank line so that the coded amount is half of the minimum transmission bits. For lines that are not completely blank, the normal codes are transmitted after the line skip bit.

· CPU interface

This interface has an 8-bit data bus, and various operation modes can be set by accessing the interface register. As interface terminals for the external DMA controller are built-in, DMA transfer between the LC8213 and the CPU bus memory is possible.

• Image memory interface

The image memory address space has 16M bytes.

The data bus size can be selected from 8-bit or 16-bit.

· DMA transfer function

DMA transfer is performed between the image memory and I/O device with the internal DMA controller. A maximum of 64k lines can be set for transferring.

 \cdot Data transfer function

Data transfer can be performed without coding/decoding between the CPU bus and image memory bus.

Pad bit processing

Pad bit processing can be selected. Pad bit processing is a function that outputs a "0" after 1 line of coded data so that it is an 8-bit unit.

Parameter settings

The following parameters can be set to the listed values.

| 1 to 8k bytes | | |
|---------------|--|--|
| 1 to 8k bytes | | |
| 1 to 64k | | |
| 0 to 64k | | |
| 0 to 64k | | |
| 1 to 64k | | |
| 0 to 255 | | |
| | | |

The document width and no. of processing bits per line can be set separately, so a part of the document can be cut and coded or decoded.



DMA controller write timing



Image memory access





Clock reset timing